

Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per Table 1

Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

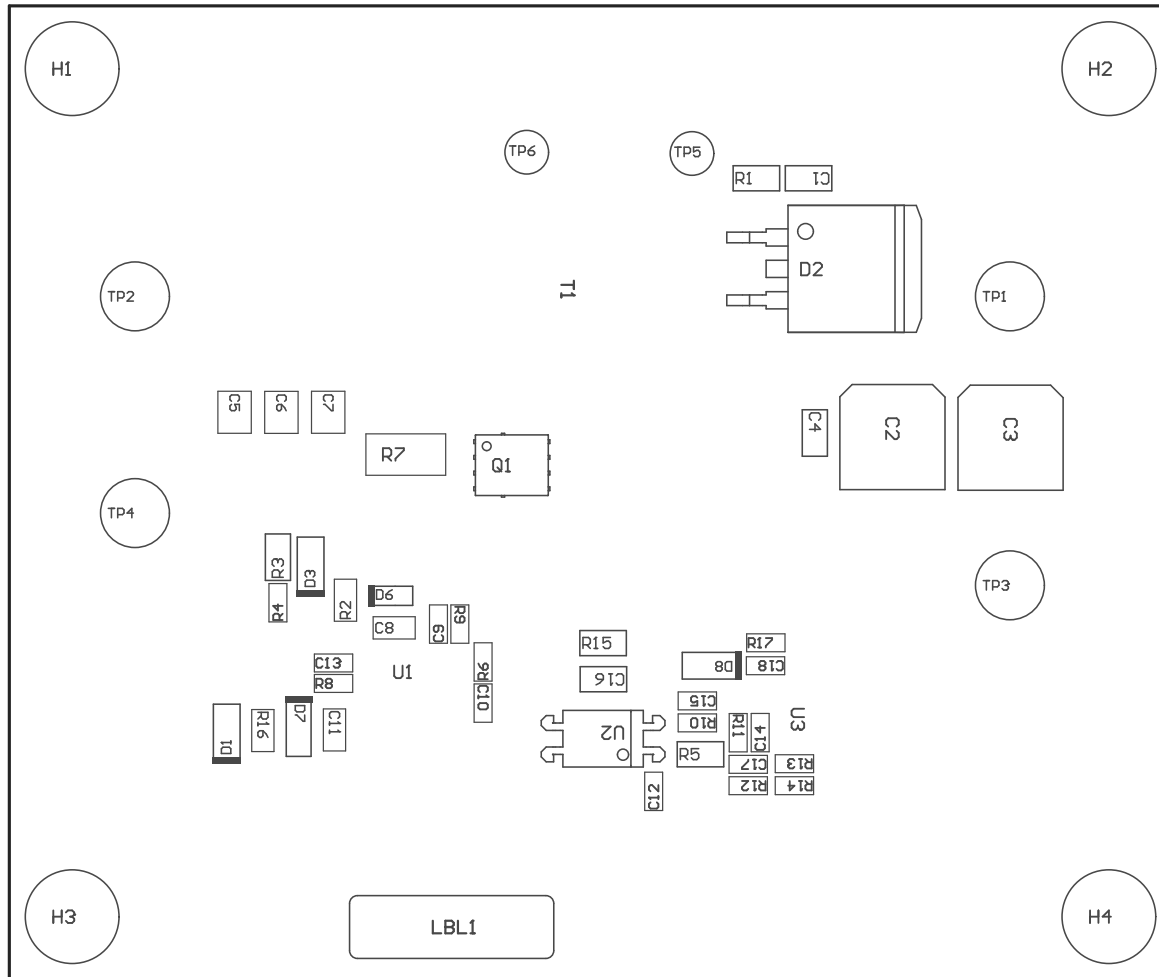
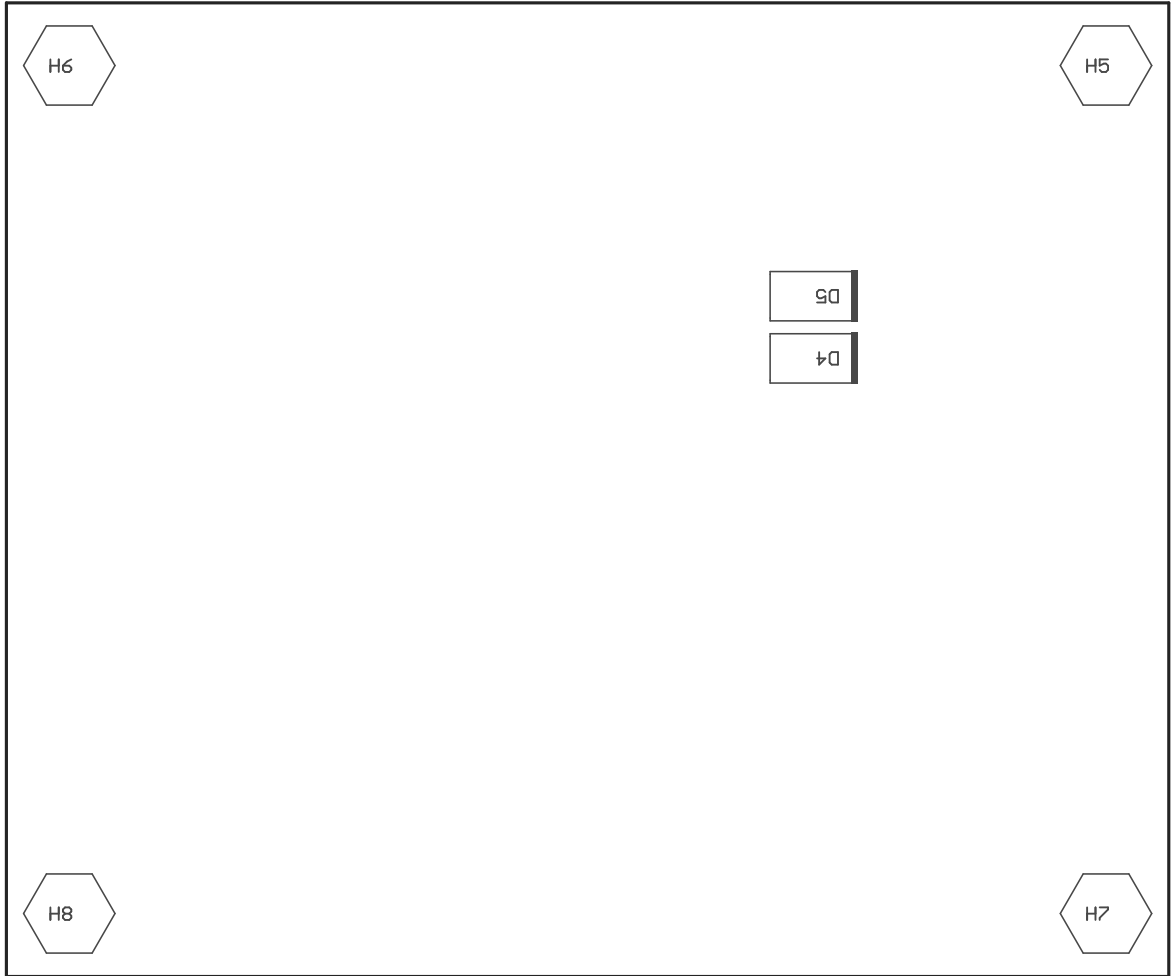


TABLE 1

Variant	Label text
001	ChangeMe!
002	ChangeMe!

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP20127	REV: A	SUN REV: Not In VersionControl
IGNORE ->			
PLOT NAME = Top Assembly Drawing	GENERATED : 11/30/2017 1:40:38 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP20127	REV: A	SVN REV: Not In VersionControl
IGNORE ->			
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11/30/2017 1:40:39 PM		TEXAS INSTRUMENTS

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